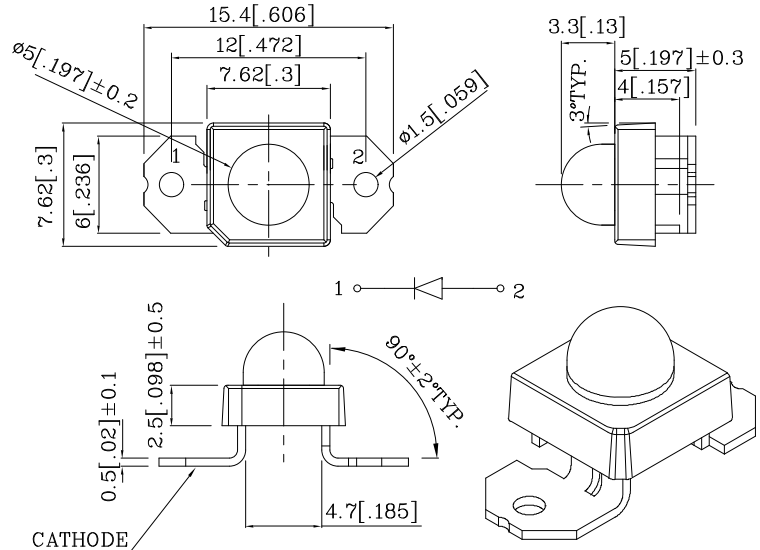


PRELIMINARY SPEC



Features:

- HIGH LUMINANCE OUTPUT.
- DESIGN FOR HIGH CURRENT OPERATION.
- SOLDERLESS MOUNTING TECHNIQUE.
- LOW POWER CONSUMPTION.
- LOW THERMAL RESISTANCE.
- LOW PROFILE.
- PACKAGED IN TUBES FOR USE WITH AUTOMATIC INSERTION EQUIPMENT.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Benefits

- *Rugged Lighting Products.
- *Electricity savings.
- *Maintenance savings.
- *Environmental Conformance.

Typical Applications

- *Automotive Exterior Lighting.
- *Solid State Lighting and Signaling.

Absolute Maximum Ratings (TA=25°C)		DG (AlInGaN)	Unit
Reverse Voltage	VR	5	V
DC Forward Current	IF	30	mA
Power Dissipation	PT	126	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-55 ~ +85	
Electrostatic Discharge Threshold (HBM)		450	V

Operating Characteristics (TA=25°C)		DG (AlInGaN)	Unit
Forward Voltage (Typ.) (IF=30mA)	VF	3.4	V
Forward Voltage (Max.) (IF=30mA)	VF	4.2	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength Of Peak Emission (Typ.) (IF=30mA)	λ P	515	nm
Wavelength Of Dominant Emission (Typ.) (IF=30mA) [1]	λ D	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=30mA)	Δλ	30	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	45	pF
Thermal Resistance (Typ.)	Rθj -pin	150	°C/W

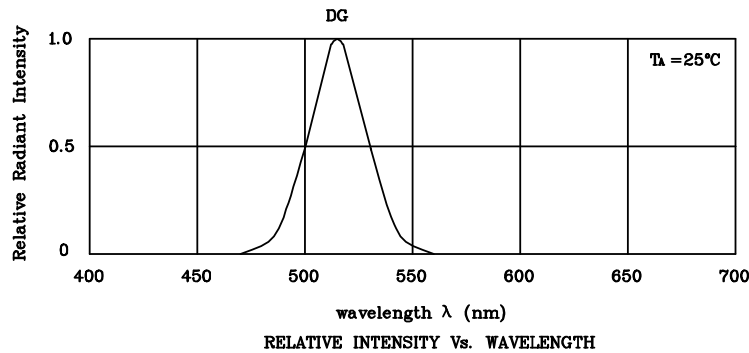
1. The dominant wavelength is derived from the CIE Chromaticity Diagram and represents the perceived color of the device.



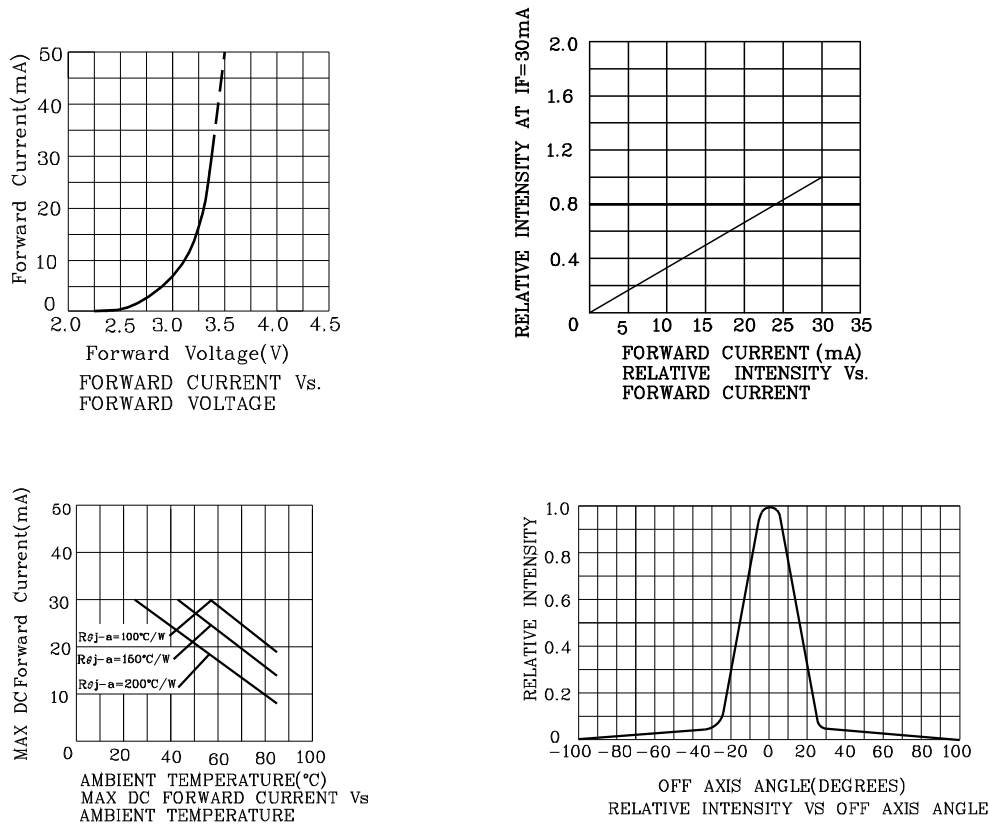


Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=30mA) mcd		Luminous Flux (IF=30mA) mlm	Wavelength nm λ P	Viewing Angle 2θ 1/2
				Min.	Typ.	Typ.		
XSDG93W	Green	AlInGaN	Water Clear	4700	7490	4200	515	30°

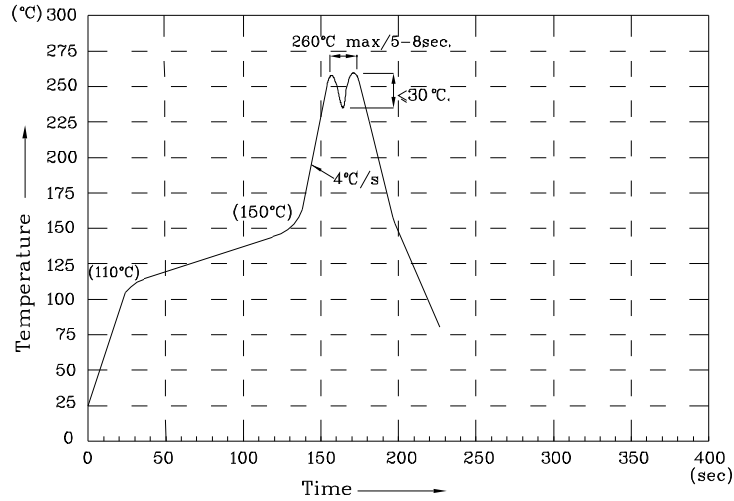
1. LUMINOUS INTENSITY IS MEASURED WITH AN INTEGRATING SPHERE AFTER THE DEVICE HAS STABILIZED.
2. θ 1/2 IS THE ANGLE FROM OPTICAL CENTERLINE WHERE THE LUMINOUS INTENSITY IS 1/2 THE OPTICAL CENTERLINE VALUE.



❖ DG

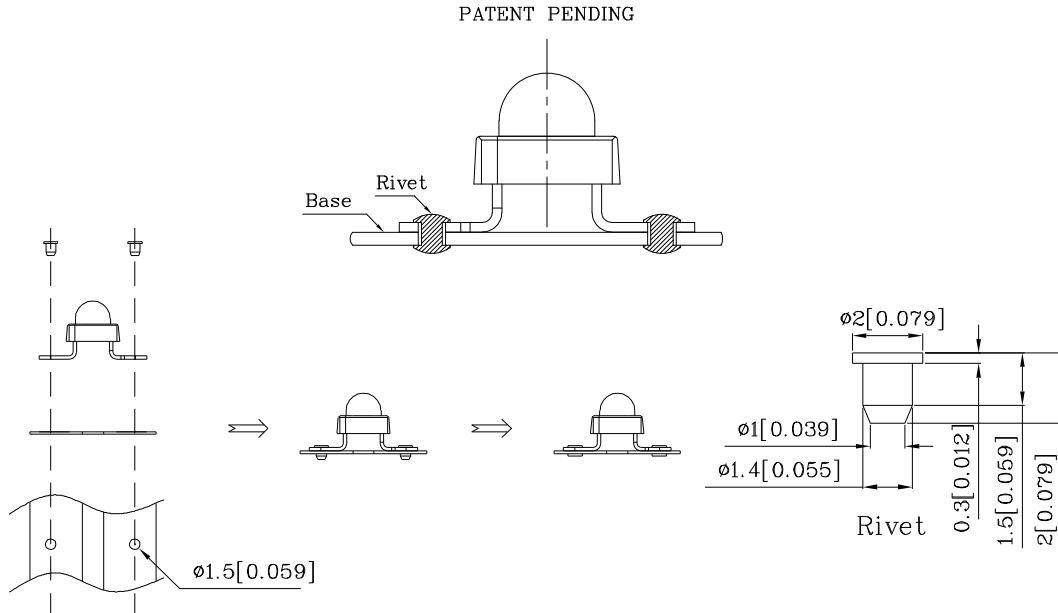


Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.



Remarks:

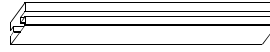
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

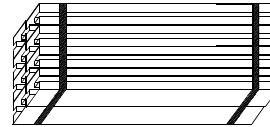
Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

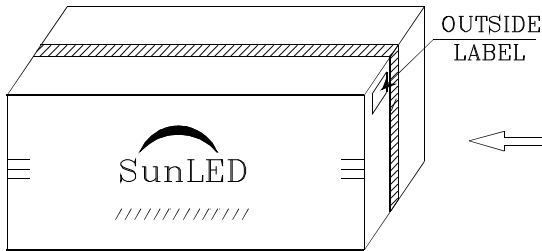
XSDG93W



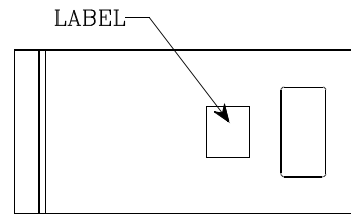
65PCS / IC TUBE




520pcs / 8pcs IC TUBE

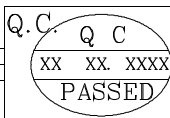



5.2K/ BOX



8pcs IC TUBE / BAG



	
P/NO : XSxxx93x	
QTY : 520 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	